

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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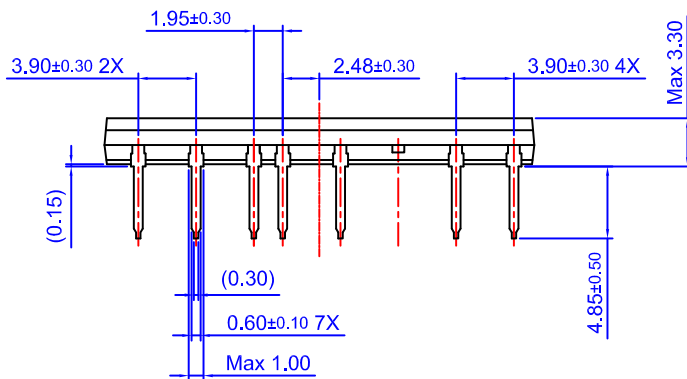
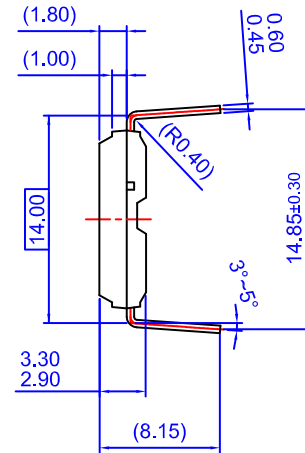
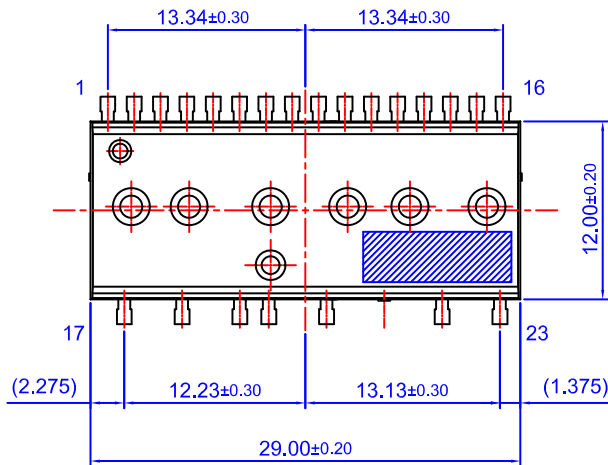
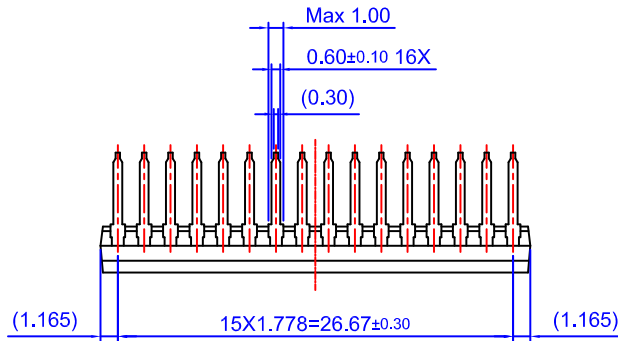


### SPM5B-023 / 23LD, PDD STD, FULL PACK, DIP TYPE

#### CASE M0DEG

#### ISSUE 0

DATE 31 JAN 2017



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
  - B) ALL DIMENSIONS ARE IN MILLIMETERS
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  - D) ( ) IS REFERENCE

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<b>DESCRIPTION:</b>	<b>SPM5B-023 / 23LD, PDD STD, FULL PACK, DIP TYPE</b>	<b>PAGE 1 OF 1</b>

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